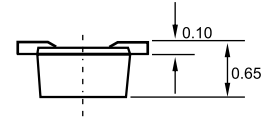
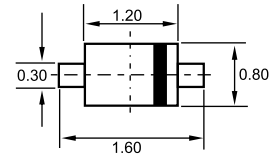


SOD-523



Dimensions in inches and (millimeters)

Features

- ✧ Low Forward Voltage Drop
- ✧ Flat Lead, Surface Mount Device at 0.60mm Height
- ✧ Extremely Small Outline Plastic Package SOD523
- ✧ Moisture Level Sensitivity 1
- ✧ Pb-free Version and RoHS Compliant
- ✧ Matte Tin (Sn) Lead Finish
- ✧ Green Mold Compound

Absolute Maximum Ratings* $T_a=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{RRM}	Maximum Repetitive Reverse Voltage	30	V
$I_{F(AV)}$	Average Rectified Forward Current	200	mA
T_J	Operating Junction Temperature Range	-55 to +125	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to +125	$^\circ\text{C}$

* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	500	$^\circ\text{C}/\text{W}$
P_D	Total Device Dissipation($T_C=25^\circ\text{C}$)	200	mW

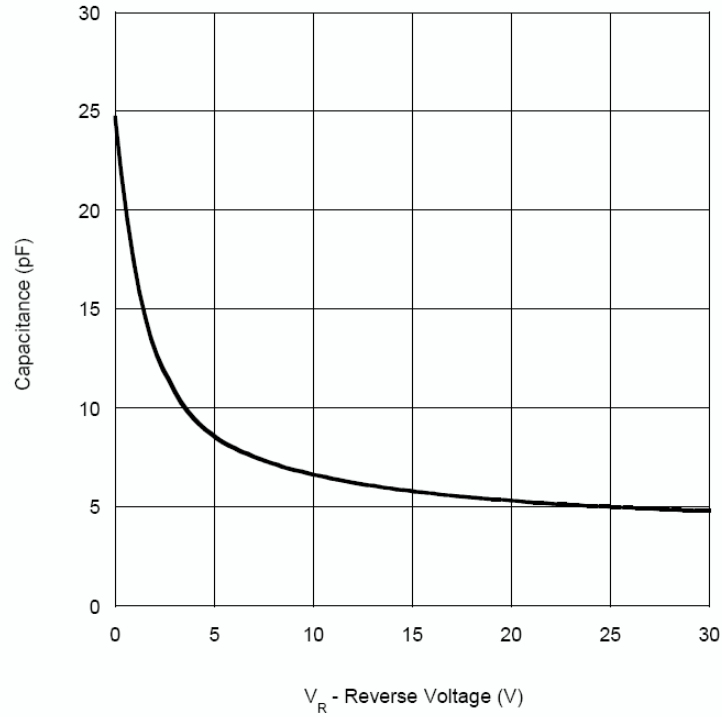
*Device mounted on FR-4 PCB minimum land pad.

Electrical Characteristics* $T_a=25^\circ\text{C}$ unless otherwise noted

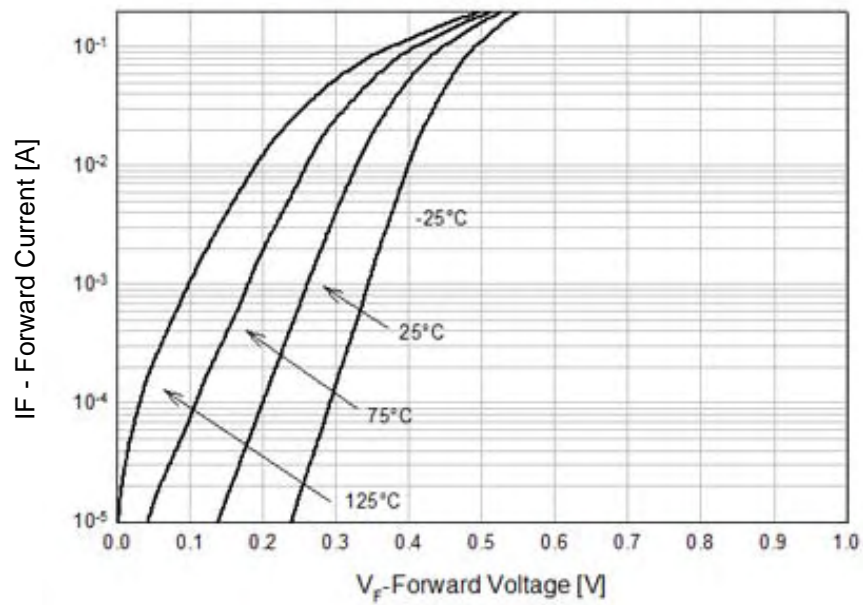
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
BV_R	Breakdown Voltage	$I_R = 500 \mu\text{A}$	30			V
I_R	Reverse Current	$V_R = 10 \text{ V}$			1	μA
V_F	Forward Voltage	$I_F = 200 \text{ mA}$			0.6	V

Typical Performance Characteristics

Capacitance vs Reverse Voltage

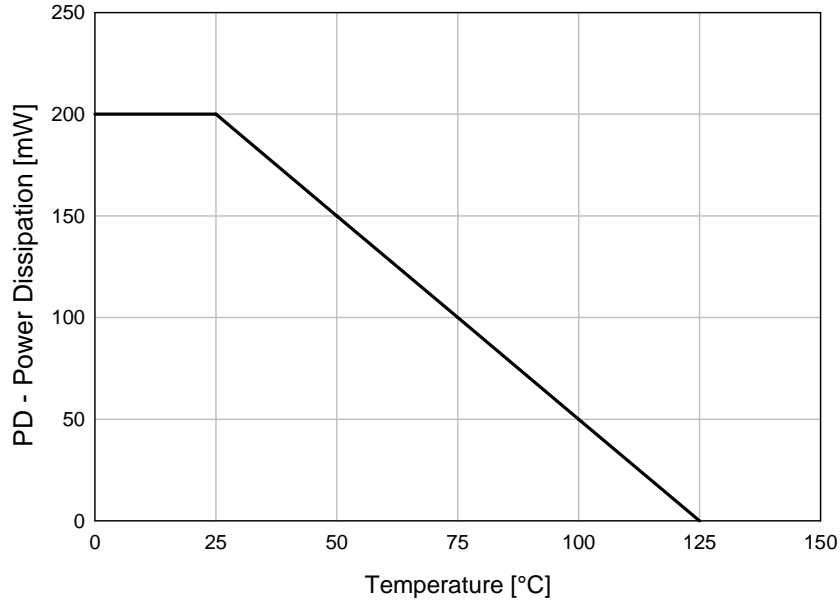


Forward Voltage vs Temperature



Typical Performance Characteristics

Power Derating Curve



Reverse Leakage Current vs Temperature

